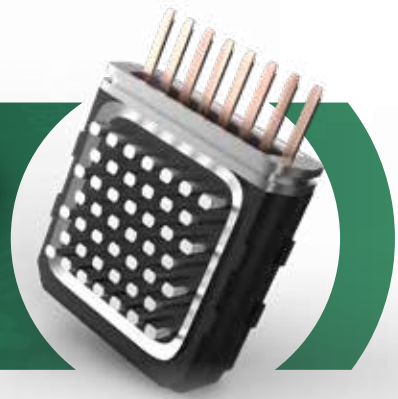


# Materials Technology for Power Module Applications



## IGBT Module

### Die-Attach

- InFORCE™ MF Sinter Paste
- Durafuse® HT High-Temperature Pb-Free Alloy
- InTACK™ Tacking Agent

### Top-Side Die Interconnect

- InFORMS® Solder Preforms and Ribbon
- Indalloy®276 High-Reliability Alloy

### DBC-Attach

- InFORMS® Solder Preforms and Ribbon
- Indalloy®133 High-Reliability Alloy

### Package-Attach

- Solder TIM (sTIM)
- InFORCE™ Sinter Paste
- Heat-Spring® Thermal Interface Materials

## SiC Molded Package

### Top-Side Die Interconnect

- InFORMS® Solder Preforms and Ribbon
- InTACK™ Tacking Agent

### Die-Attach

- InFORCE™ MF Sinter Paste
- InTACK™ Tacking Agent

## Package-Attach

- Indalloy® 301 LT Alloy
- InFORMS® Solder Preforms and Ribbon
- InFORCE™ Sinter Paste



Learn more: [www.indium.com/power](http://www.indium.com/power)

**From One Engineer To Another®**

All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified.  
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